



Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment

Marketing Name / Model

[List multiple models if applicable.]

HP 7500 2.4T 8p G/10G and 2p 40G MPU (JH209A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#
Socket Spanner	
Continuous vacuum desoldering system	
Desoldering tip	
Damp sponge	
Flux-cored solder	
tweezers	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove film 1 and shielding finger 3 from part 2;
2. Unscrew the screws on assembly 4, then remove assembly 4 from assembly 2;
3. Unscrew the screws on PCB 4-4, then remove 4-1 from PCB 4-4;
4. Unscrew the screws on heatsink 4-3, then remove heatsink 4-3;
5. Remove heatsink 4-2;
6. Unscrew the screw nuts on PCB 4-5, then remove PCB 4-5;
7. Remove battery from PCB 4-4, see figure 4-figure 8;
8. Unscrew the screws on PCB 2-2, then remove bottom plate 2-1;
9. Unscrew the screws on guiding sets 2-3, then remove guiding sets 2-3;
10. Remove heatsink 2-4;
11. Unscrew the screws on strengthening bar 2-5, then remove 2-5;

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

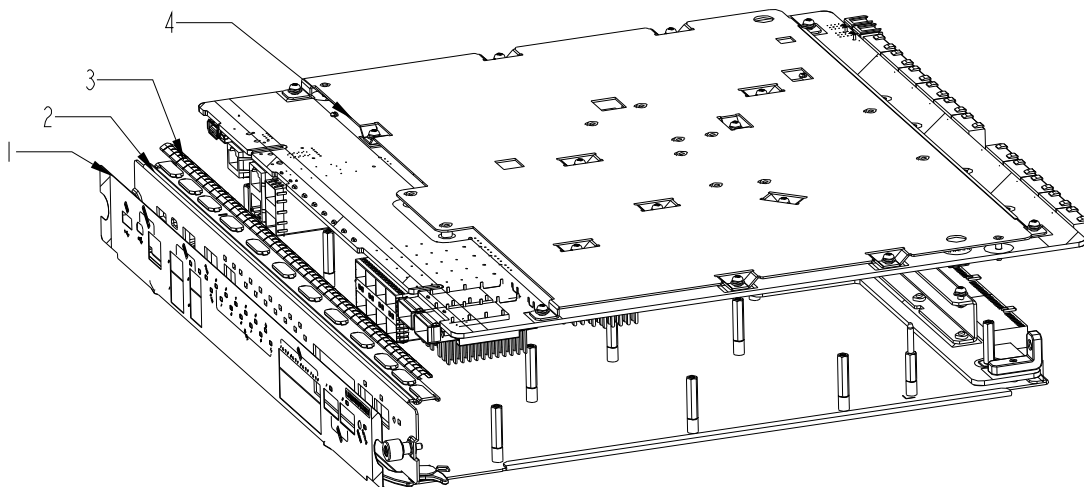


Figure 1 Treatments to the product

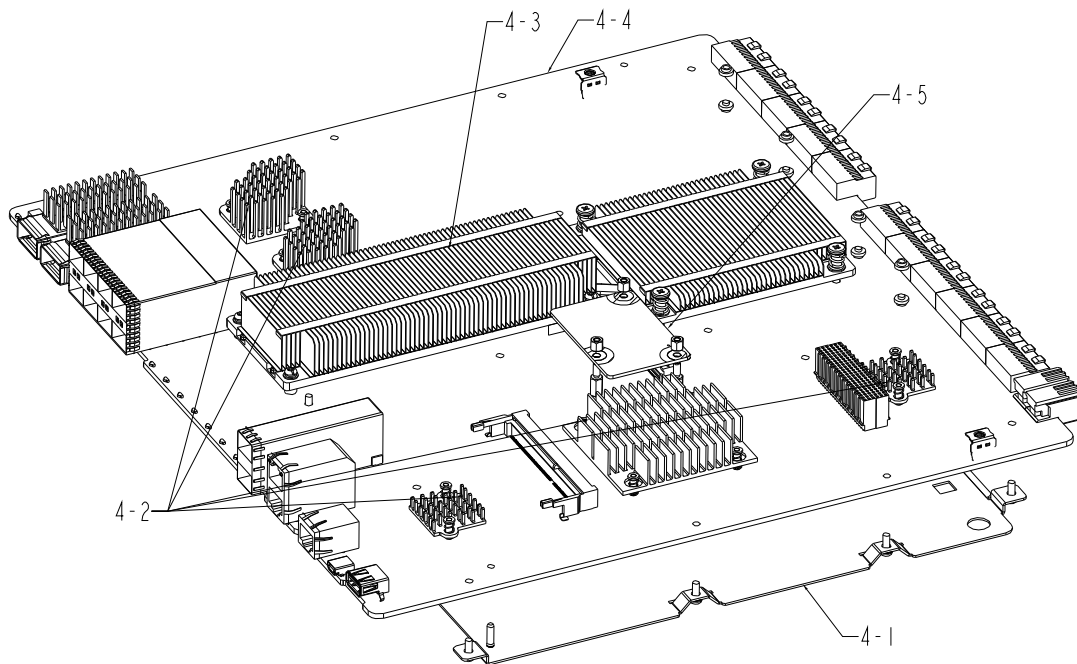


Figure 2 Treatments to the assembly 4

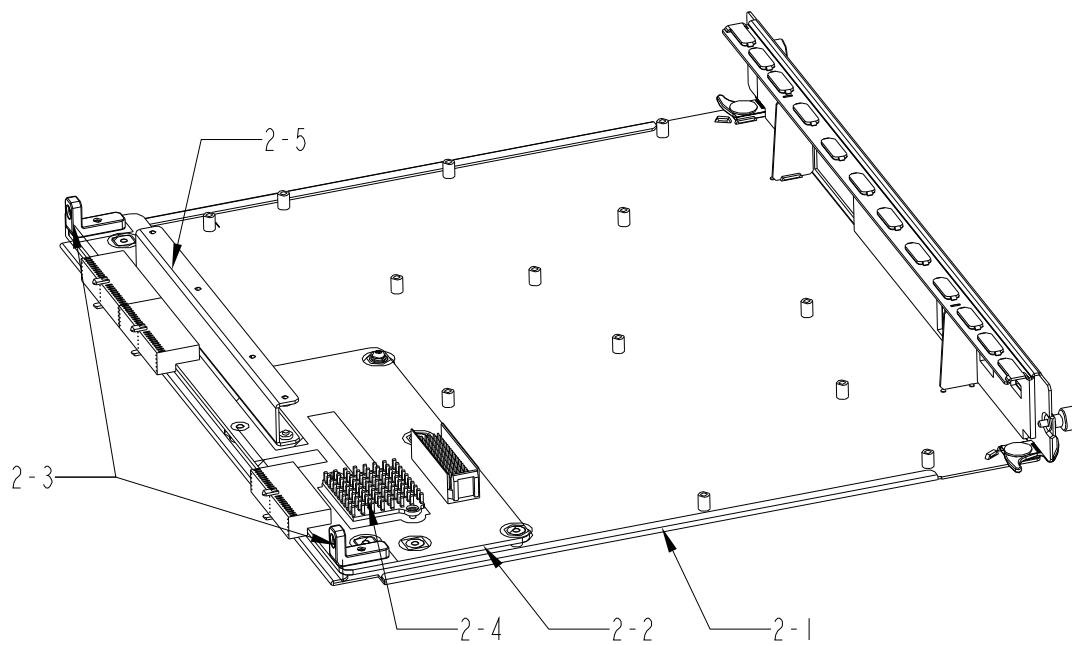


Figure 3 Treatments to the assembly 5

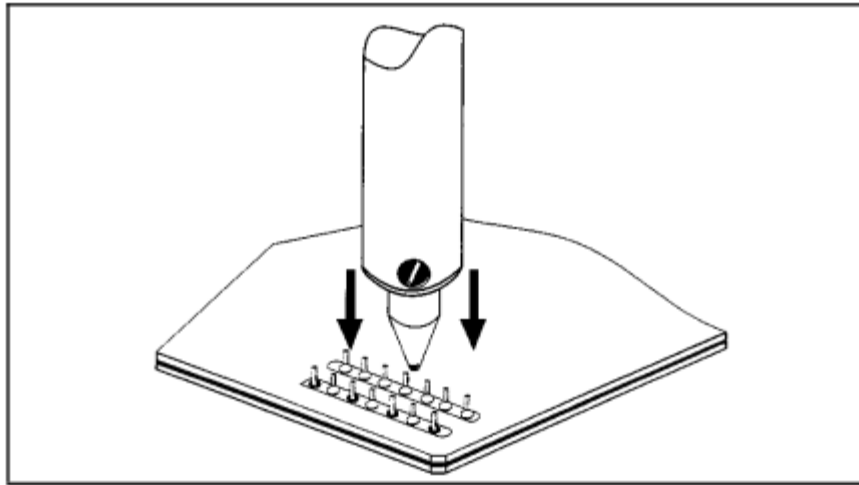


Figure 4 Position Tip

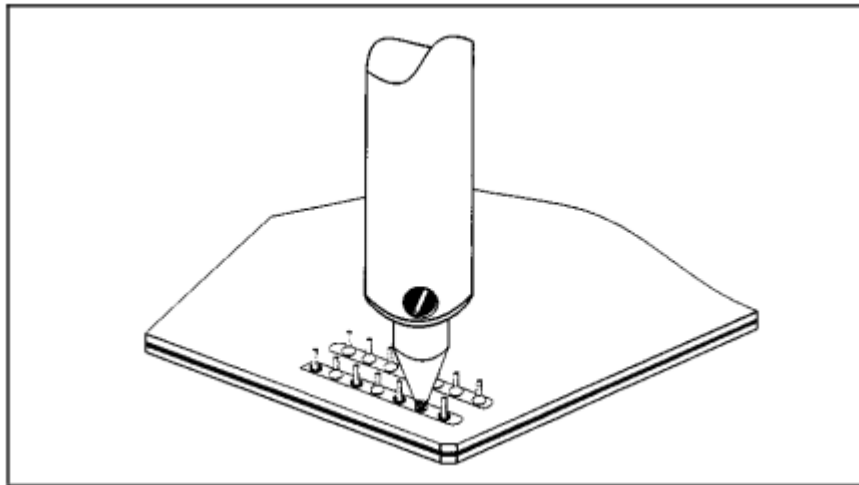


Figure 5 Melt Solder

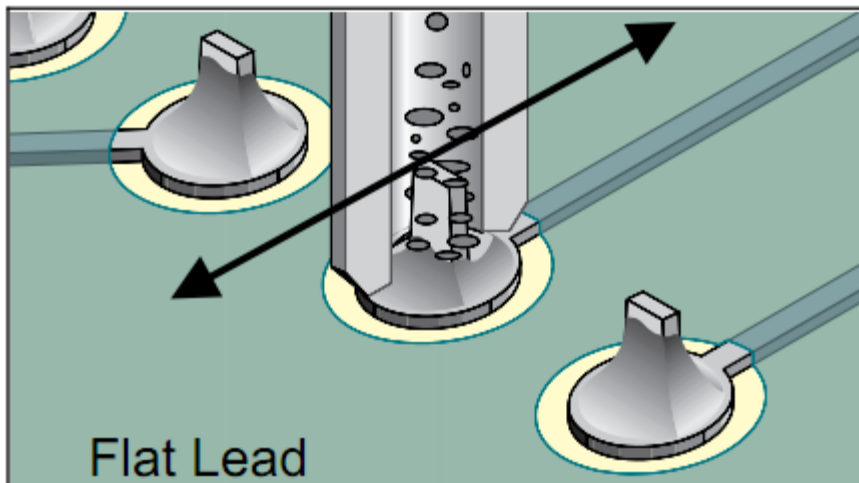


Figure 6 Move Lead & Apply Vacuum

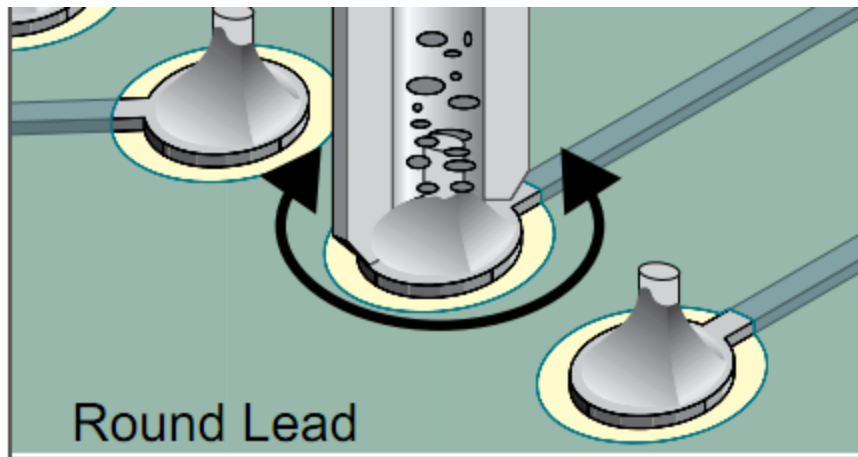


Figure 7 Move Lead & Apply Vacuum

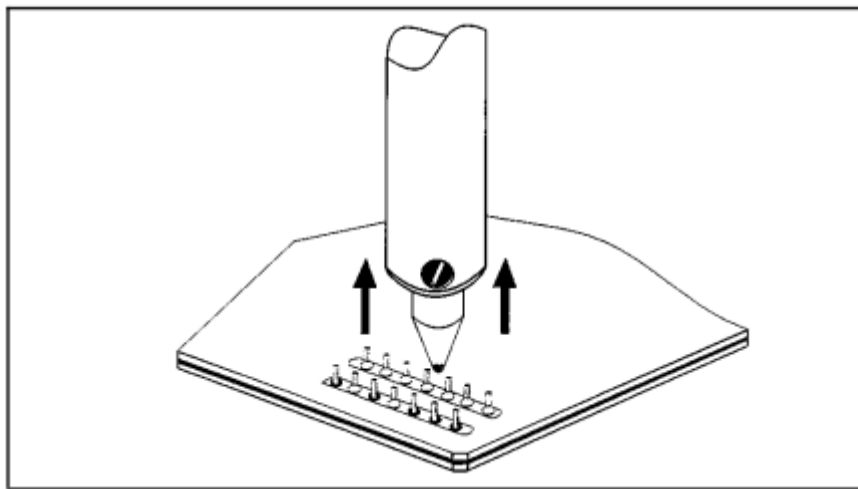


Figure 8 Lift Handpiece

3.3 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details
1		PC	3.9	0.09%		Pla recycling
2	2-1	Fe	1502	35.47%		Fe recycling
	2-2	Complex PCB	233	5.0%	The surface If PCB is greater than 10 square centimeters	
	2-3	Zn	23.4	0.55%		Zn recycling
	2-4	Al	9.3	0.22%		Al recycling
	2-5	Fe	89.8	2.12%		Fe recycling
3		Be-Cu	2.7	0.06%		Cu recycling
4	4-1	Fe	734	17.34%		Fe recycling
	4-2	Al	76.4	1.8%		Al recycling
	4-3	Al	375	8.86%		Al recycling
	4-4	Complex PCB	1174	27.73%	The surface If PCB is greater than 10 square centimeters	
	4-5	Complex PCB	10.6	0.25%	The surface If PCB is greater than 10 square centimeters	

4. Revised record

Date	Version	Author	Modify content
2015.5.18	V0	Liao Wenqing	Initial version